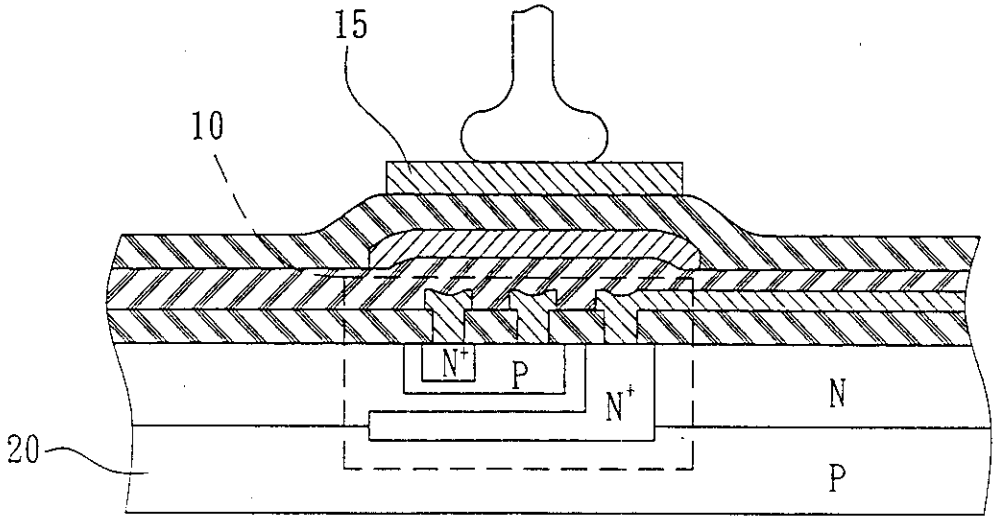



FIG. 1
(PRIOR ART)

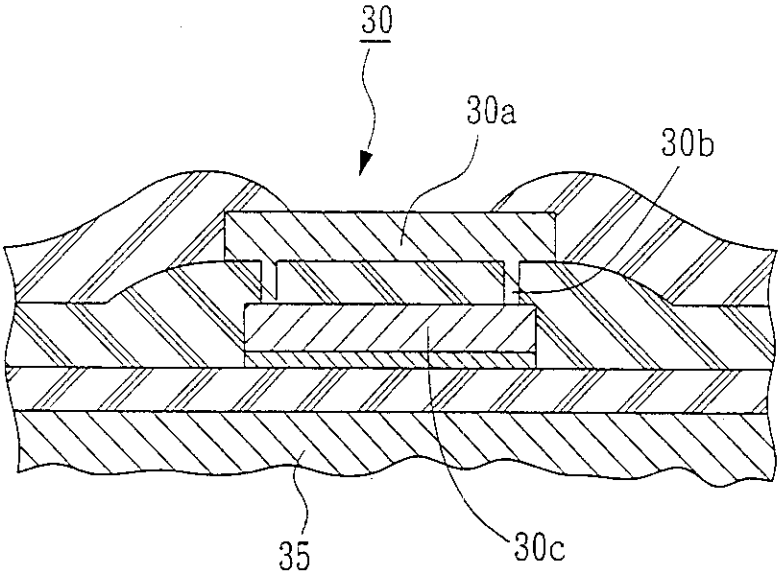



FIG. 2
(PRIOR ART)

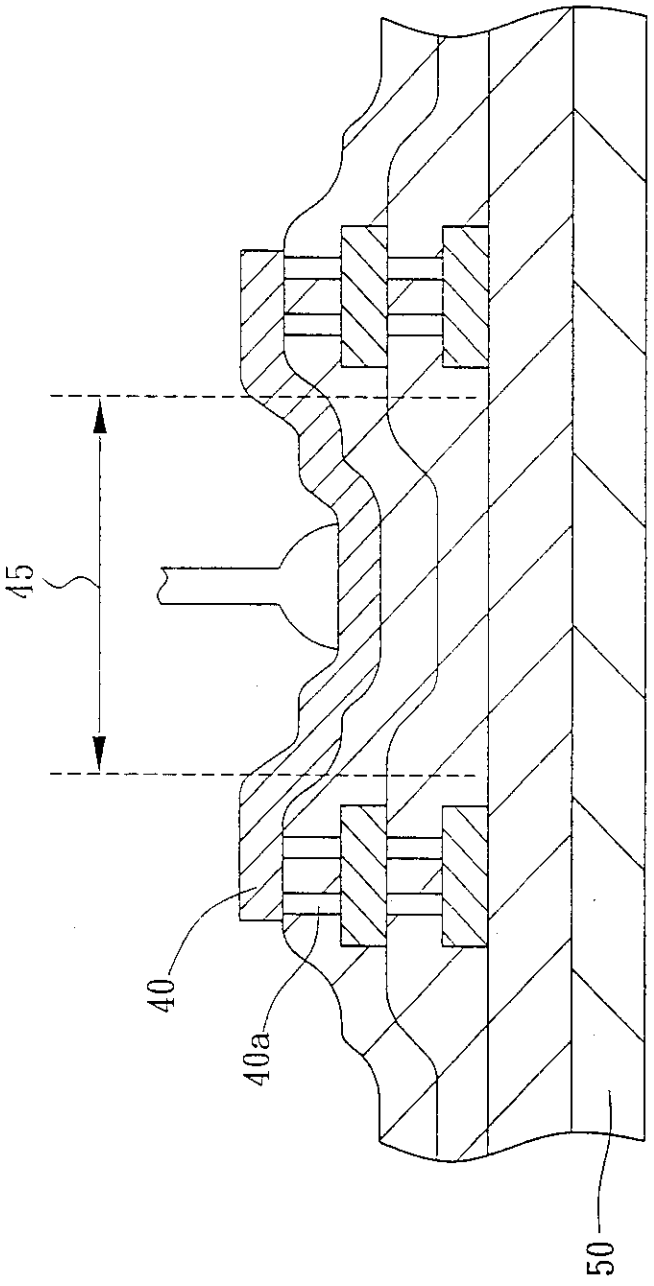



FIG. 3
(PRIOR ART)

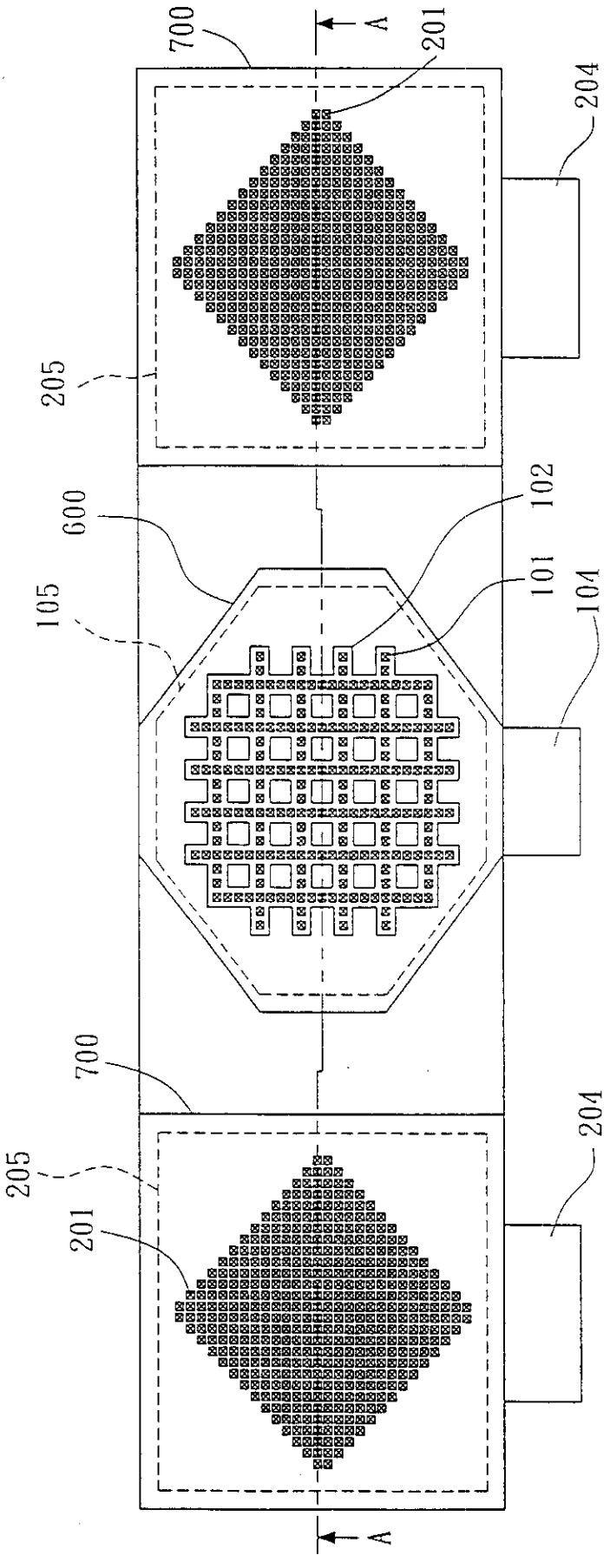



FIG. 4

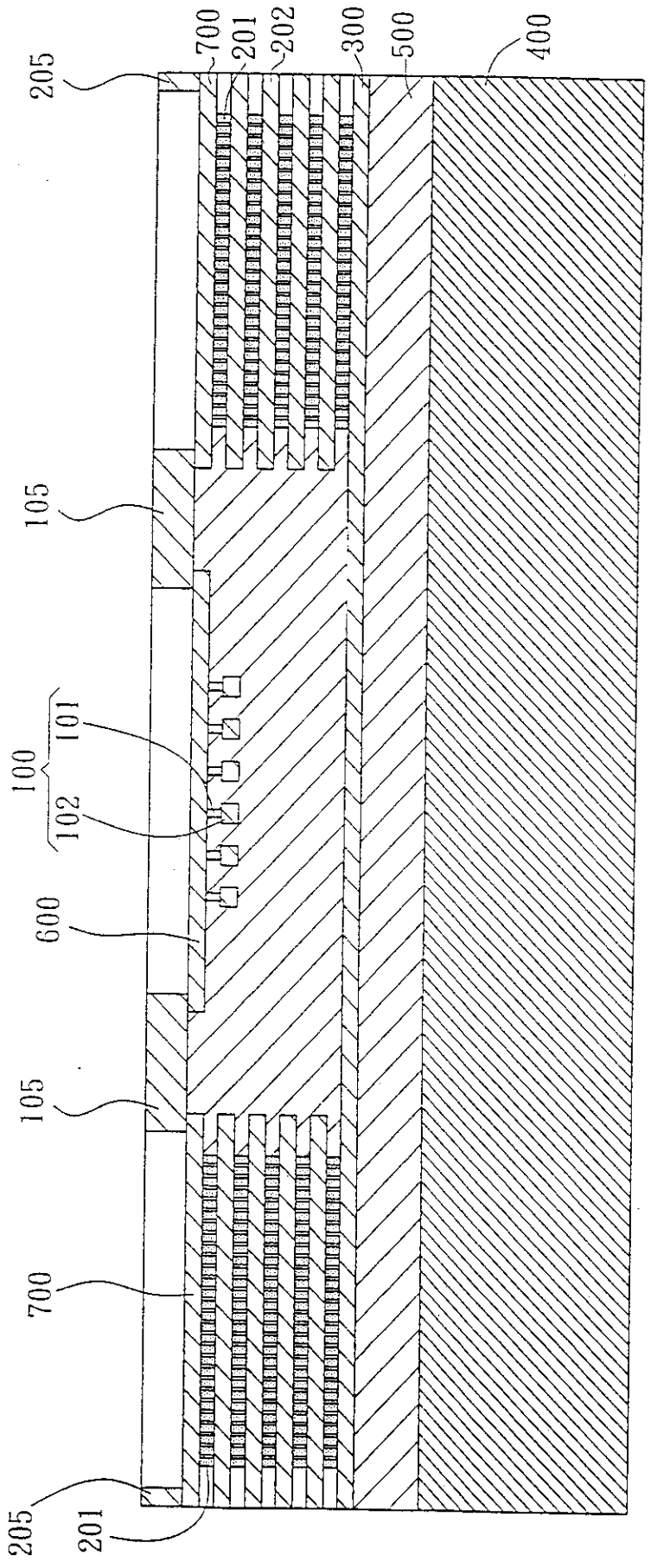



FIG. 5

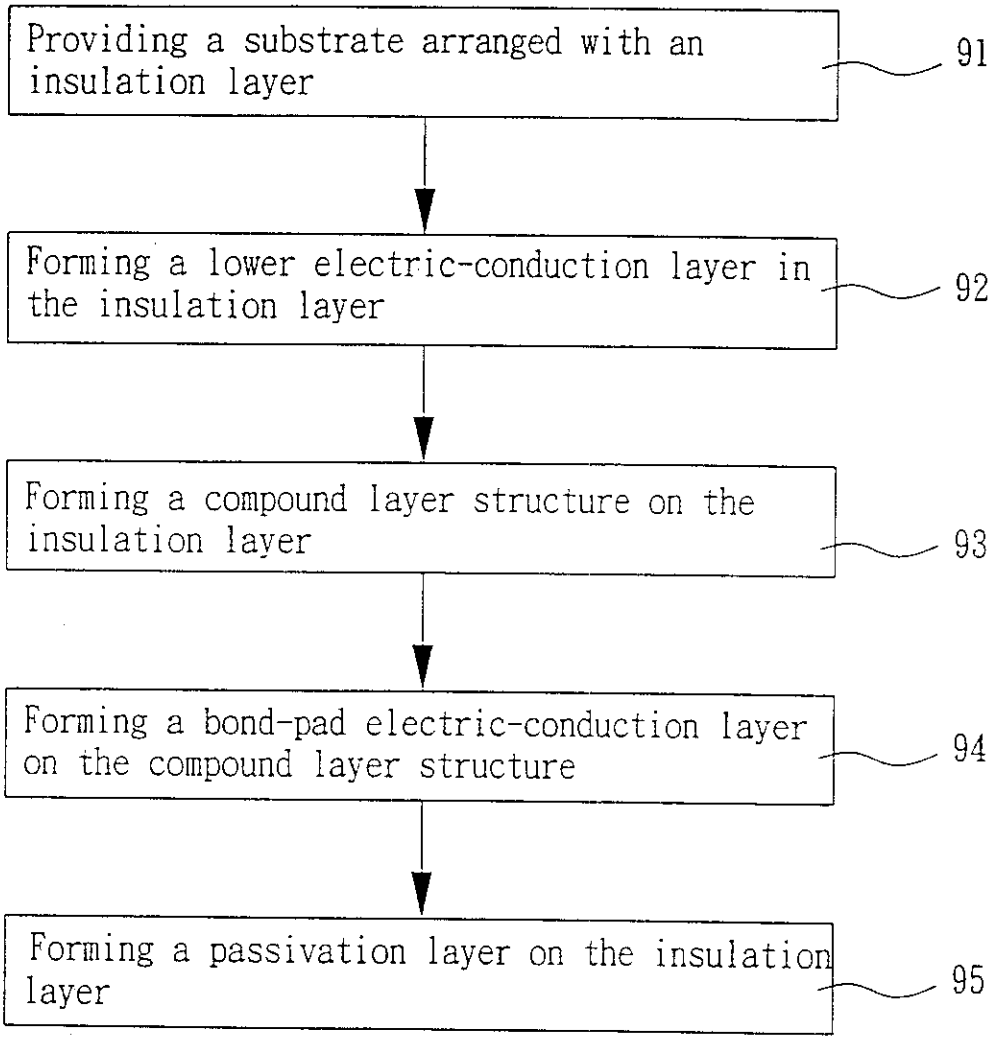

Providing a substrate arranged with an insulation layer
91
Forming a lower electric-conduction layer in the insulation layer
92
Forming a compound layer structure on the insulation layer
93
Forming a bond-pad electric-conduction layer on the compound layer structure
94
Forming a passivation layer on the insulation layer
95

FIG. 6